

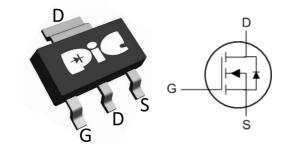
## General Description

This PAN00TB06QB N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

### > Feature

- •Green Device Available
- ■Super Low Gate Charge
- ●Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- ●SOT-223 package design

### SOT-223



## Application

- Motor and Load Control
- Power Management in White LED System
- ●Push Pull Converter
- ●LCD TV Inverter & AD/DC Inverter Systems.

## > Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	Vos	100	V
Gate-Source Voltage	Vgs	±20	V
Continuous Drain Current, Vgs @ 10V1	In@Ta=25°C	3	А
Continuous Drain Current, Vgs @ 10V1	ID@Ta=70°C	2.4	А
Pulsed Drain Current2	Ірм	15	А
Total Power Dissipation₃	Pd@Ta=25°C	2	W
Storage Temperature Range	Тѕтс	-55 to 150	°C
Operating Junction Temperature Range	TJ	-55 to 150	°C
Thermal Resistance Junction-ambient 1	Reja	85	°C/W
Thermal Resistance Junction-Case <sub>1</sub>	Rejc	24	°C/W



## Electrical Characteristics (T<sub>J</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	BVDSS	Vgs=0V , In=-250uA	100			V	
BVDSS Temperature Coefficient	Δ BVDSS/Δ TJ	Reference to 25°C , ID=-1mA		0.082		V/°C	
Static Drain-Source On-Resistance2	Rds(on)	Vgs=10V, ID=3A		60	75	mΩ	
		Vgs=4.5V , Ip=2A		65	82	1115.2	
Gate Threshold Voltage	VGS(th)	Vgs=Vps , Ip =-250uA	1.2	1.6	2.5	V	
V <sub>GS(th)</sub> Temperature Coefficient	Δ VGS(th)	VGS=VDS , ID =-250UA		-4.8		mV/°C	
Drain-Source Leakage Current	lpss	Vds=80V , Vgs=0V , TJ=25°C			-1	uA	
	IDSS	Vds=80V , Vds=0V , TJ=55°C			-5		
Gate-Source Leakage Current	Igss	Vgs=±20V, Vps=0V			±100	nA	
Forward Transconductance	gfs	VDS=5V, ID=3A		5.8		S	
Gate Resistance	Rg	VDS=0V , VGS=0V , f=1MHz		1.4	2.8	Ω	
Total Gate Charge (10V)	Qg			40	56		
Gate-Source Charge	Qgs	Vps=80V , Vgs=10V , Ip=3A		7.3	10.2	nC	
Gate-Drain Charge	Qgd			7	9.8		
Turn-On Delay Time	T <sub>d(on)</sub>			9.2	18.4		
Rise Time	Tr	VDD=50V, VGS=10V,		22	40		
Turn-Off Delay Time	T <sub>d(off)</sub>	Rg=3.3ΩID=3A		41	82	ns	
Fall Time	Tf			19.6	39		
Input Capacitance	Ciss			2400	3360		
Output Capacitance	Coss	Vps=15V , Vgs=0V , f=1MHz		100	140	pF	
Reverse Transfer Capacitance	Crss			82	115		

## Diode Characteristics

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous Source Current <sub>1,4</sub>	ls	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			3	Α
Pulsed Source Current <sub>2,4</sub>	Ізм	VG=VD=0V, Force Current			15	Α
Diode Forward Voltage2	VsD	Vgs=0V , Is=1A , TJ=25°C			1.2	V
Reverse Recovery Time	trr			41		nS
Reverse Recovery Charge	Qrr	F=3A , dl/dt=100A/μs , T <sub>J</sub> =25°C		25		nC

#### Note:

<sup>1.</sup> Pulse width limited by maximum junction temperature.

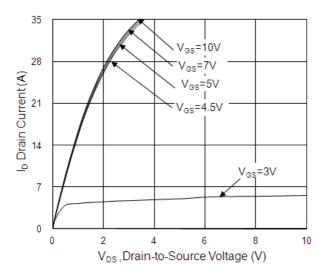
<sup>2.</sup>The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

<sup>3.</sup>Ensure that the channel temperature does not exceed 150°C.

<sup>4.</sup>The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



## > Typical Characteristics



**Fig.1 Typical Output Characteristics** 

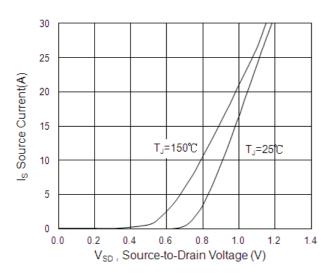


Fig.3 Forward Characteristics of Reverse

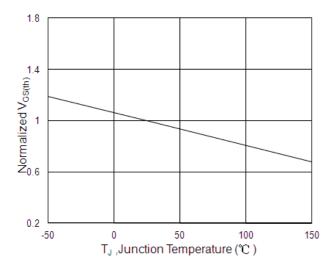


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

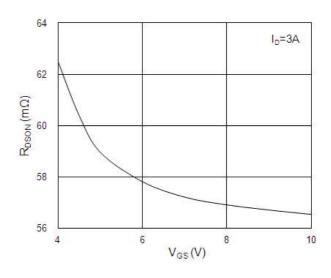


Fig.2 On-Resistance vs. Gate-Source

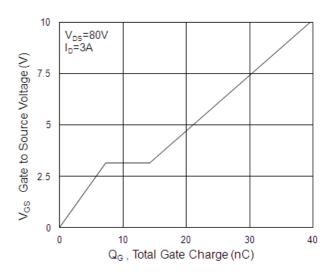


Fig.4 Gate-Charge Characteristics

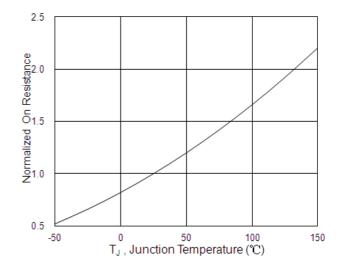
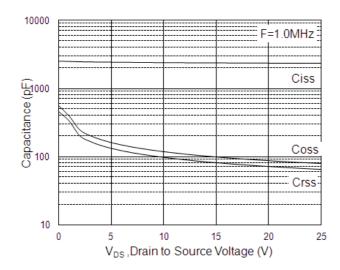


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





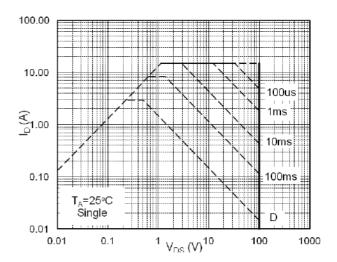


Fig.7 Capacitance

Fig.8 Safe Operating Area

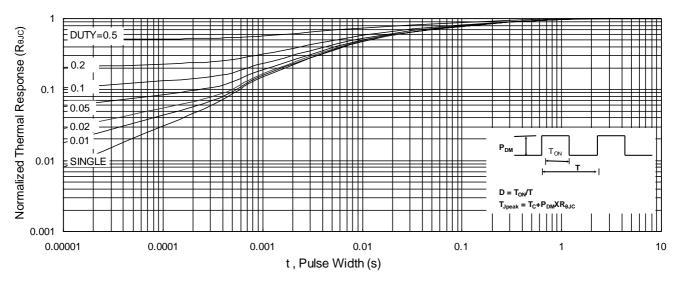


Fig.9 Normalized Maximum Transient Thermal Impedance

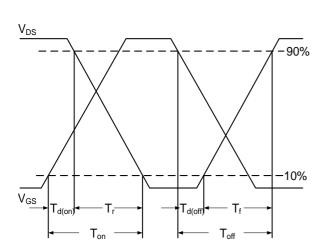


Fig.10 Switching Time Waveform

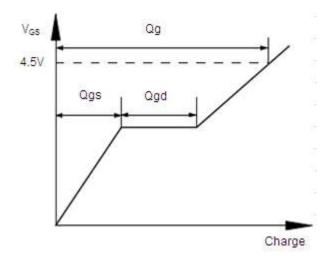
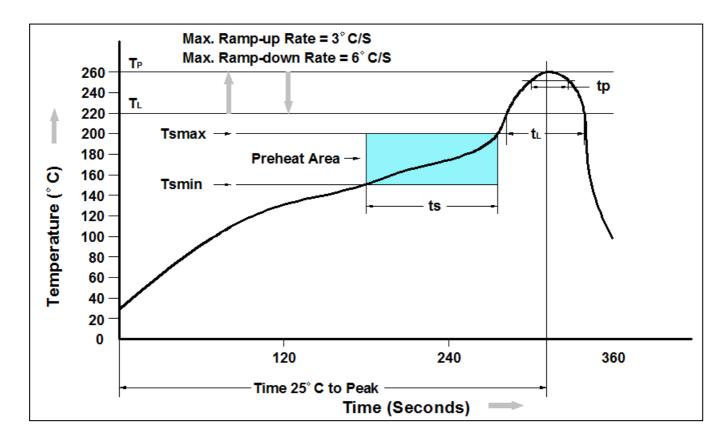


Fig.11 Gate Charge Waveform



## Recommand IR Reflow Soldering Thermal Profile



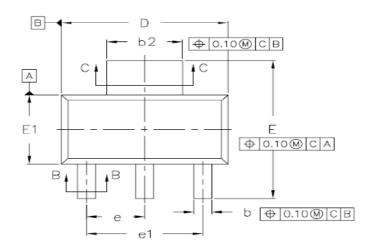
Profile Feature	Pb-Free Assembly Profile		
Temperature Min. (Tsmin)	150°C		
Temperature Max. (Tsmax)	200°C		
Time (ts) from (Tsmin to Tsmax)	60-120 seconds		
Average Ramp-up Rate (tL to tP)	3°C/second max.		
Liquidous Temperature (TL)	217°C		
Time (tL) Maintained Above (TL)	60 – 150 seconds		
Peak Temperature	260°C +0°C /-5°C		
Time (tP) within 5°C of actual Peak Temperature	30 seconds		
Ramp-down Rate (TP to TL)	6°C/second max		
Time 25°C to Peak Temperature	8 minutes max.		

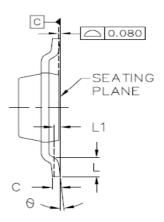
## Ordering Information

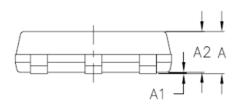
Part Number	Description	Quantity
PAN00TB06QB	SOT-223 Reel	3000 pcs



# Package Information (SOT-223)







Ş	COMMON					
MB P	MM		INCH			
l s	MIN.	MAX.	MIN.	MAX.		
Α		1.80		0.071		
A1	0.02	0.10	0.001	0.004		
A2	1.50	1.70	0.059	0.067		
b	0.66	0.84	0.026	0.033		
b1	0.60	0.79	0.024	0.031		
b2	2.90	3.10	0.114	0.122		
b3	2.84	3.05	0.112	0.120		
С	0.23	0.35	0.009	0.014		
c1	0.23	0.33	0.009	0.013		
D	6.30	6.70	0.248	0.264		
E	6.70	7.30	0.264	0.287		
E1	3.30	3.70	0.130	0.146		
е	2.30 BSC.		0.091	BSC.		
e1	4.60 BSC.		0.182	BSC.		
L	0.81		0.032			
L1	0.25	0.25 BSC.		O BSC.		
- 9	0,	10°	0,	10°		



# PAN00TB06QB

N-Ch 100V Fast Switching MOSFET  $V_{DS}$ =100V,  $I_{D}$ =3.0A,  $RDS_{(ON)}$ =75m $\Omega$ 

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